

Substrate comprising vias and associated manufacturing methods**ABSTRACT**

5 The invention relates to a substrate comprising a first layer (30) based on a
semiconductive material, and a second layer (31) surmounting the first layer. The substrate
(3) comprises a plurality of buried hollow vias (32) extending from the second layer (31)
over a portion of the first layer (30). The invention further relates to the method for
manufacturing the substrate and the method for manufacturing a microelectronic device
10 using the substrate. The substrate comprising hollow vias for a subsequent use, the
manufacturing of the vias is facilitated.

Fig. 2A